



US 20220386459A1

(19) **United States**(12) **Patent Application Publication**  
**FUKUSHIMA et al.**(10) **Pub. No.: US 2022/0386459 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **WIRING CIRCUIT BOARD AND  
PRODUCING METHOD THEREOF****Publication Classification**(51) **Int. Cl.****H05K 1/02** (2006.01)**H05K 3/46** (2006.01)**H05K 3/18** (2006.01)(52) **U.S. Cl.**CPC ..... **H05K 1/0298** (2013.01); **H05K 3/4644**  
(2013.01); **H05K 3/18** (2013.01); **H05K**  
**2203/0703** (2013.01)(71) Applicant: **NITTO DENKO CORPORATION,**  
Osaka (JP)(72) Inventors: **Rihito FUKUSHIMA,** Osaka (JP);  
**Hayato TAKAKURA,** Osaka (JP);  
**Naoki SHIBATA,** Osaka (JP)(73) Assignee: **NITTO DENKO CORPORATION,**  
Osaka (JP)(21) Appl. No.: **17/775,797**(22) PCT Filed: **Oct. 13, 2020**(86) PCT No.: **PCT/JP2020/038643**

§ 371 (c)(1),

(2) Date: **May 10, 2022**(30) **Foreign Application Priority Data**

Nov. 12, 2019 (JP) ..... 2019-204942

**ABSTRACT**

A wiring circuit board includes a base insulating layer; a first wiring disposed on the base insulating layer; an intermediate insulating layer disposed on the base insulating layer so as to cover the first wiring; a second wiring disposed on the intermediate insulating layer; a single layer first terminal, disposed on the base insulating layer, and electrically connected to the first wiring; and a single layer second terminal, disposed on the base insulating layer, and electrically connected to the second wiring. The first terminal is continuous with the first wiring. The second terminal is discontinuous from the second wiring. The wiring circuit board further includes a connecting portion disposed on the base insulating layer and continuous with the second terminal to electrically connect to the second wiring.

